Special Issue

Integrated Circuit Design in Post-Moore Era

Message from the Guest Editor

This Special Issue provides a platform for researchers to report their most recent progress in the field of integrated circuits, including integrated circuit design, technology, packaging and testing, etc. It will bring together, from a global perspective, scientists, researchers, end-users, and industry to exchange ideas, advance knowledge and report key issues of the post-Moore era technology. Topics of interest for this Special Issue include but are not limited to:

- Analog integrated circuit design (including radio frequency circuit)
- System on Chip (SoC)
- Random access memory (RAM)
- Digital circuit design
- IC measurement and test
- IC package
- Key devices in integrated circuits

For more information on the Special Issue, please visit LINK https://www.mdpi.com/journal/applsci/special_issues/69520O5E8I

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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